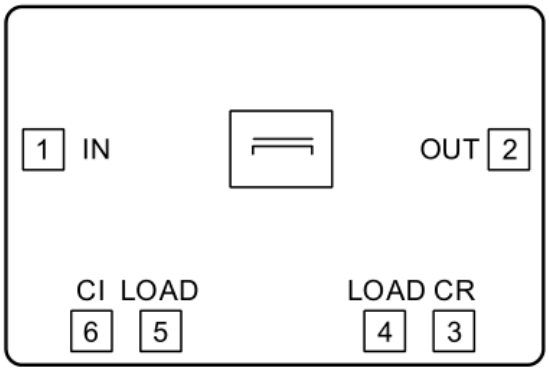
Features

- Operating Frequency: 2-18GHz
- Insertion Loss: 1.25dB @ 18GHz
- Coupling: 12dB
- Coupling Flatness: ± 2dB
- Die Size: 3 x 1.5 x 0.1 mm

Functional Block Diagram



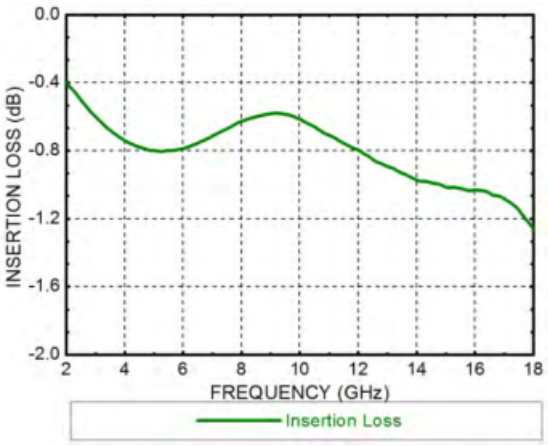
Typical Applications

- Test Instrumentation
- Microwave Radio & VSAT
- Military & Space
- Telecom Infrastructure
- Fiber Optics

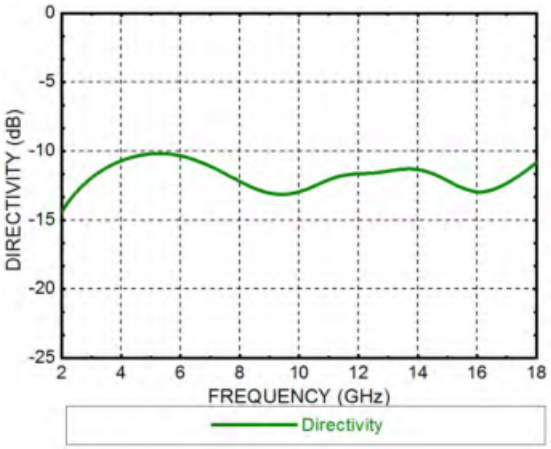
Electrical Specifications

Parameters	Min.	Typ.	Max.	Units
Frequency Range		2-18		GHz
Insertion Loss		1		dB
Coupling	10.3	12	14.3	dB
Coupling Flatness		±2		dB
Return Loss		15		dB
Isolation		20		dB

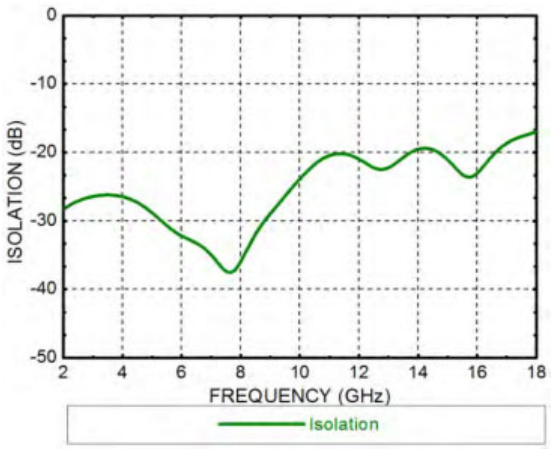
Insertion Loss



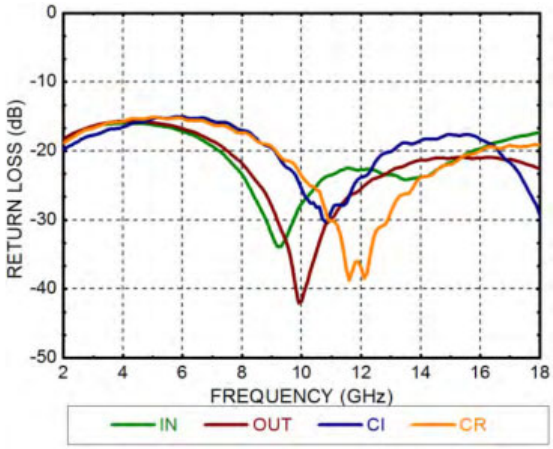
Coupling



Isolation

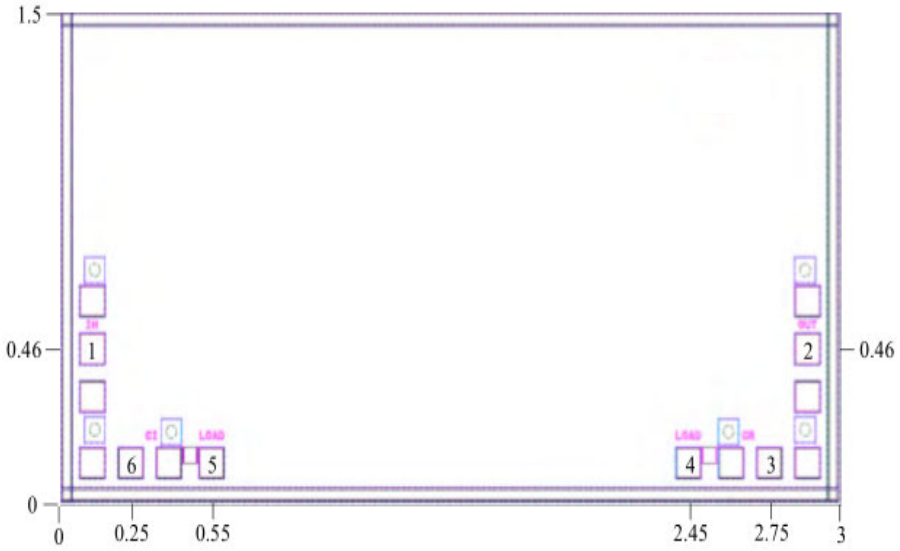


Return Loss



Outline Drawing:

All Dimensions in mm



Pad Description

Pad Number	Function	Description
1	IN	RF input
2	OUT	RF output
3	CR	Negative direction coupling port
4, 5	LOAD	50Ω Load
6	CI	Positive direction coupling port
Die bottom	GND	Die bottom must be connected to RF/DC ground.

Notes:

1. Die thickness: 100um
2. Typical bond pad is 100*100 μm^2
3. Bond pad metalization: Gold
4. Backside metalization: Gold
5. Backside of the die is grounded
6. No connection required for unlabeled bond pads